

MATERIALS & FINISHES

BODY: BRASS
PLATED GOLD

CONTACT: BERYLLIUM COPPER
PLATED GOLD

INSULATOR: TEFLON

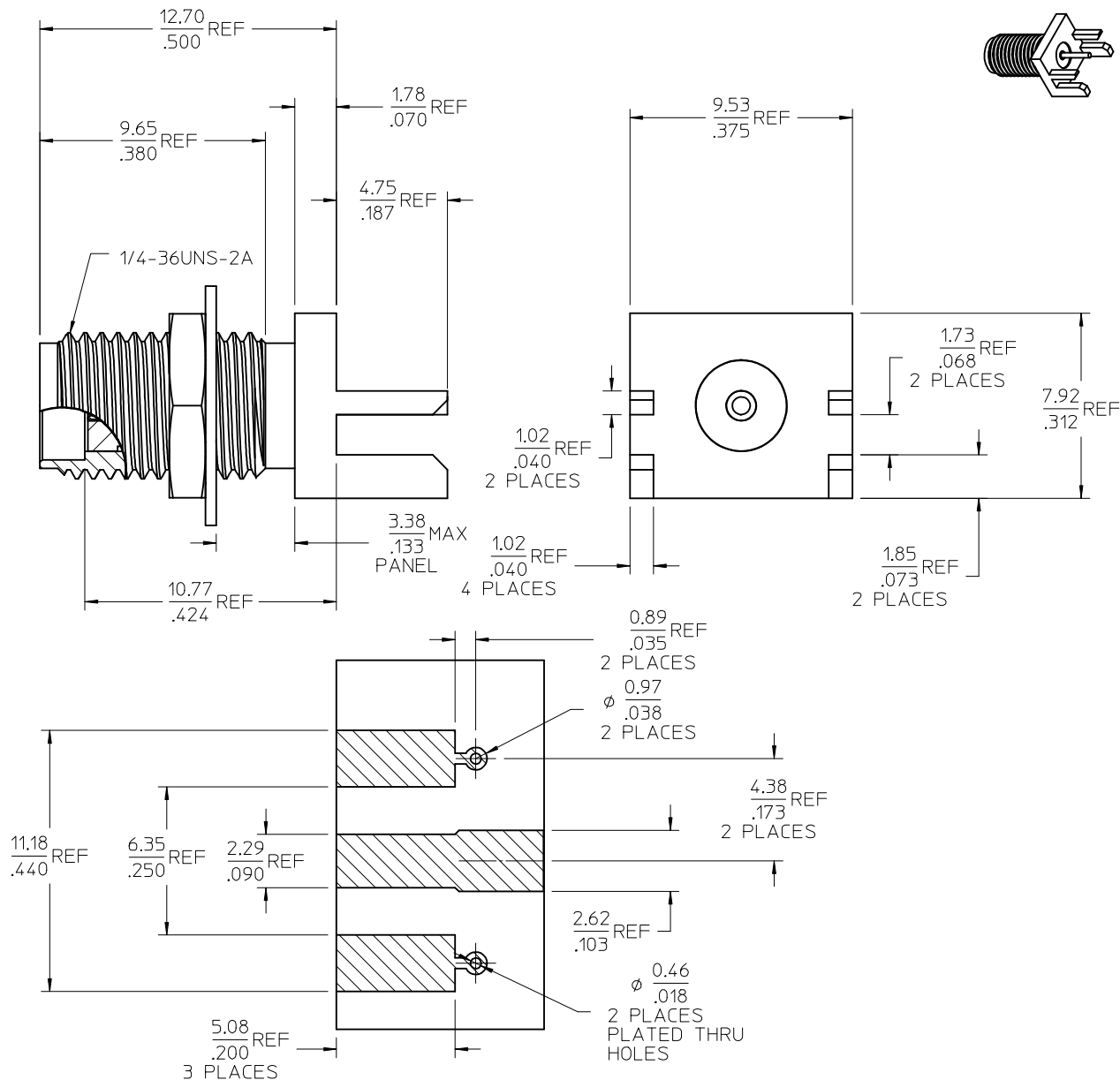
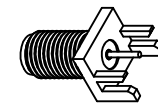
JAM NUT: BRASS
PLATED GOLD

LOCK WASHER: PHOSPHOR BRONZE
PLATED GOLD

HARDWARE:

JAM NUT: 7.877/310 HEX X 1.557/061

LOCK WASHER: ϕ 10.267/404 X ϕ 6.657/262 X .467/018



RECOMMENDED PCB LAYOUT

BOARD THICKNESS 1.577/062

PART # 73251-1290

MIL-STD-348A, FIG. 310.2	INTERFACE
SPECIFICATION	DESCRIPTION

CHG: ADDED .424 DIM AND THD	EC NO: URF2015-0141	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	DRWN:JLE02 2014/10/24	DESCRIPTION	mm INCH	MM/IN	METRIC	☉	
CHKD:SSS 2014/10/24	APPR:WSP/INK 2014/10/27	▽=0	4 PLACES ± --- ± ---	DRAWN BY	DATE	TITLE	
		▽=0	3 PLACES ± --- ± ---	CHECKED BY	DATE	SMA, JACK EDGEMOUNT FOR .062 PCB SMA-J/PCB, EWR-2864	
			2 PLACES ± --- ± ---	SSS	2000/08/00		MOLEX INCORPORATED
			1 PLACE ± --- ± ---	APPROVED BY	DATE		
			ANGULAR ± 2 °	GMH	2000/08/00		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	DOCUMENT NO.		SHEET NO.
				732511290	SD-73251-129		1 OF 1
				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
				C			